PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
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HIDETAKA MIYAKE	04/21/2014

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14364188

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SIGNATURE:	/Derrick Tyson/
DATE SIGNED:	06/10/2014

Total Attachments: 1
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PMAA-14038-U

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by
(Insert Name(s) & Address(es) of ASSIGNEE(S))

Mitsubishi Electric Corporation
7-3, Marunouchi 2-chome, Chiyoda-ku, TOKYO 100-8310 JAPAN

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
(Title of Invention)

WIRE ELECTRIC-DISCHARGE MACHINING DEVICE, WIRE ELECTRIC-DISCHARGE MACHINING METHOD, THIN-PLATE MANUFACTURING METHOD, AND SEMICONDUCTOR WAFER MANUFACTURING METHOD

relating to International Patent Application PCT/JP2012/082696 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on ____________________; *(Insert date of execution of application, if not concurrent)*

(b) filed on ____________________,

Serial No. ___/____________________;

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

1)	Atsushi Itokazu *(Signature)*	Atsushi ITOKAZU *(Type Name)*	April 21, 2014 *(Date)*
2)	Hidetaka Miyake *(Signature)*	Hidetaka MIYAKE *(Type Name)*	April 21, 2014 *(Date)*
3)	*(Signature)*	*(Type Name)*	*(Date)*
4)	*(Signature)*	*(Type Name)*	*(Date)*
5)	*(Signature)*	*(Type Name)*	*(Date)*
6)	*(Signature)*	*(Type Name)*	*(Date)*